PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: NISSIN ELECTRIC CO., LTD. transfer of rights to SHARP KABUSHIKI KAISHA

CONVEYING PARTY DATA

| Name | Execution Date |
|---------------------------|----------------|
| NISSIN ELECTRIC CO., LTD. | 08/26/2010 |

RECEIVING PARTY DATA

| Name: | SHARP KABUSHIKI KAISHA | |
|-----------------|------------------------------|--|
| Street Address: | 22-22, Nagaike-cho, Abeno-ku | |
| City: | Osaka-shi, Osaka | |
| State/Country: | Japan | |
| Postal Code: | 545-8522 | |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|----------------|---------|
| Patent Number: | 6358313 |

CORRESPONDENCE DATA

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NAME OF SUBMITTER: Lee Cheng

Total Attachments: 2

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PATENT REEL: 025077 FRAME: 0224

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the undersigned assignee **NISSIN ELECTRIC CO., LTD.**, does hereby assign, sell and transfer unto:

SHARP KABUSHIKI KAISHA, of the address

22-22, Nagaike-cho, Abeno-ku, Osaka-shi, Osaka 545-8522, JAPAN

(hereinafter ASSIGNEE), its successors, assigns, and legal representatives, 100% of its right, title and interest for the United States, and countries foreign thereto, in and to the inventions relating to

U.S. Patent No. 6,358,313 Entitled: METHOD OF MANUFACTURING A CRYSTALLINE SILICON BASE SEMICONDUCTOR THIN FILM

(assignment recorded at Reel 010675, Frame 0665)

and in and to said patents and patent applications, including any divisions and continuations thereof, and in and to any and all Letters Patents of the United States, and countries foreign thereto, which may be granted for said inventions, and in and to any all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patents

And, the undersigned warrants and covenants that it is an assignee of these patents and patent applications and has the full and unencumbered right to sell and assign 100% of its interests herein and that it has not executed and will not execute any document or instrument in conflict herewith;

And, the undersigned further covenants and agrees that at any time upon request of said ASSIGNEE, its successors, legal representatives or assigns he will communicate to said ASSIGNEE, its successors, legal representatives or assigns all information known to him relating to said inventions or patent applications and that he will execute and deliver any papers, make all rightful oaths, testify in any legal proceedings and perform all other lawful acts deemed necessary or desirable by said ASSIGNEE, its successors, legal representatives or assigns to perfect title to said inventions, to said applications including divisions and continuations thereof and to any and all Letters Patent which may be granted therefor or thereon, including reissues or extensions, in said ASSIGNEE, its successors, or assigns or to assist said ASSIGNEE, its successors, legal representatives or assigns in obtaining, reissuing or enforcing Letters Patent of the United States for said invention.

ASSIGNOR

NISSIN ELECTRIC CO., LTD.

47, Umezu Takase-cho, Ukyo-ku, Kyoto-shi

PATENT REEL: 025077 FRAME: 0225 Kyoto 615-8686, JAPAN

Holling Unaw Date: Aug. 16, 2010
President of
Nissin El

Nissin Electric Co., Ltd.

REEL: 025077 FRAME: 0226